

# EE 330

## Lecture 3

- Selected profiles with ISU ties
- Integrated Circuit Design Flow
- Basic Concepts
  - Feature Sizes
  - Manufacturing Costs
  - Yield
- Key Historical Developments

## Top 10 Semiconductor Sales Leaders 2016-2019

March 11, 2019, anysilicon

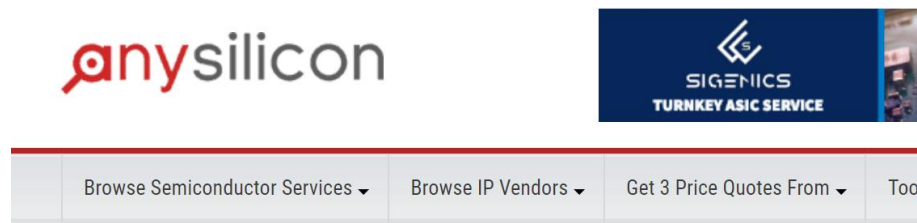
### Top 10 Worldwide Semiconductor Sales Leaders

2016			2017			2018			2019F		
Rank	Company	Sales (\$B)	Company	Sales (\$B)	Change	Company	Sales (\$B)	Change	Company	Sales (\$B)	Change
1	Intel	\$57.0	Samsung	\$65.9	48.8%	Samsung	\$78.5	19.2%	Intel	\$70.6	1.0%
2	Samsung	\$44.3	Intel	\$61.7	8.2%	Intel	\$69.9	13.2%	Samsung	\$63.1	-19.7%
3	TSMC (2)	\$29.5	TSMC (2)	\$32.2	9.1%	SK Hynix	\$36.8	37.6%			
4	Qualcomm (1)	\$15.4	SK Hynix	\$26.7	79.5%	TSMC (2)	\$34.2	6.4%			
5	Broadcom (1)	\$15.2	Micron	\$23.9	76.7%	Micron	\$31.0	29.6%			
6	SK Hynix	\$14.9	Broadcom (1)	\$17.8	16.9%	Broadcom (1)	\$18.5	3.7%			
7	Micron	\$13.5	Qualcomm (1)	\$17.0	10.5%	Qualcomm (1)	\$16.4	-3.8%			
8	TI	\$12.5	TI	\$13.9	11.3%	Toshiba*	\$14.9	12.1%			
9	Toshiba	\$10.9	Toshiba	\$13.3	21.9%	TI	\$14.9	6.8%			
10	NXP	\$9.5	Nvidia (1)	\$9.4	36.1%	Nvidia (1)	\$12.0	27.1%			
Top 10 Total (\$B)		\$222.8	—	\$281.9	26.5%	—	\$327.0	16.0%			
Semi Market (\$B)		\$364.0	—	\$445.2	22.3%	—	\$504.1	13.2%	—	\$468.9	-7.0%

Source: IC Insights (1) Fabless (2) Pure-Play foundry

\*Includes Toshiba Memory

# Why did Samsung's position change so much?



## Top 10 Semiconductor Sales Leaders 2016-2019

March 11, 2019, anysilicon

IC Insights is currently updating its 2019-2023 semiconductor market forecasts that will be presented later this month in the March Update, the first monthly Update to the 500-page, 2019 edition of The McClean Report—A Complete Analysis and Forecast of the Integrated Circuit Industry (released in January 2019).

For 2019, a steep 24% drop in the memory market is forecast to pull the total semiconductor market down by 7%. With 83% of Samsung's semiconductor sales being memory devices last year, the memory market downturn is expected to drag the company's total semiconductor sales down by 20% this year. Although Intel's semiconductor sales are forecast to be relatively flat in 2019, the company is poised to regain the number 1 semiconductor supplier ranking this year (Figure 1), a position it held from 1993 through 2016.

# Selected Semiconductor Company Profiles

(with Iowa ties)

## Texas Instruments:

- World's largest producer of analog semiconductors at \$8.2B, over 100% larger than closest competitor
- Ranks 1<sup>st</sup> in DSP
- Ranks 9<sup>th</sup> in World in semiconductor sales

Number of employees: 30,000

2018 sales: \$15.80B

2018 income: \$5.6B  
(after taxes)

Average annual sales/employee: \$474K

Average annual earnings/employee: \$187K

(data from TI quarterly reports)



Jerry Junkins

Past CEO of TI  
ISU EE Class of '59

# Selected Semiconductor Company Profiles

(with Iowa ties)

## Intel:

World's largest producer of semiconductors

Cofounders: Robert Noyce and Gordon Moore

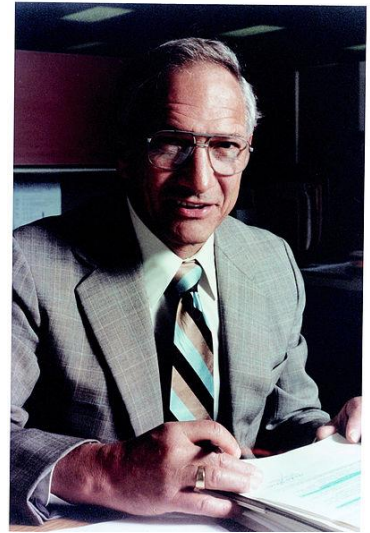
Number of employees (2019) : 110,000

2018 sales: \$71B

2018 income: \$21B

Average annual sales/employee: \$645K

Average annual earnings/employee: \$190K



Robert Noyce  
BA Grinnell 1949

Noyce is also the co-inventor of the integrated circuit !

# Selected Semiconductor Company Profiles

(with Iowa ties)

Marvell:

Cofounders: Sehat Sutardja (CEO), Welli Dai and Pantas Sutardja

Number of employees: 5200

2018 sales: \$2.9B

2018 income: \$520M

Average annual sales/employee: \$513K

Average annual earnings/employee: \$100K

Fabless Semiconductor Company



Sehat Sutardja

**BSEE ISU**  
(approx 1985)

# Selected Semiconductor Company Profiles

(with Iowa ties)

Maxim: Founded in April 1983, profitable every year since 1987

Tunc Doluca joined Maxim in October 1984,  
appointed President and CEO in 2007

Number of employees: 7150

2018 sales: \$2.5B

2018 income: \$467M

Average annual sales/employee: \$350K

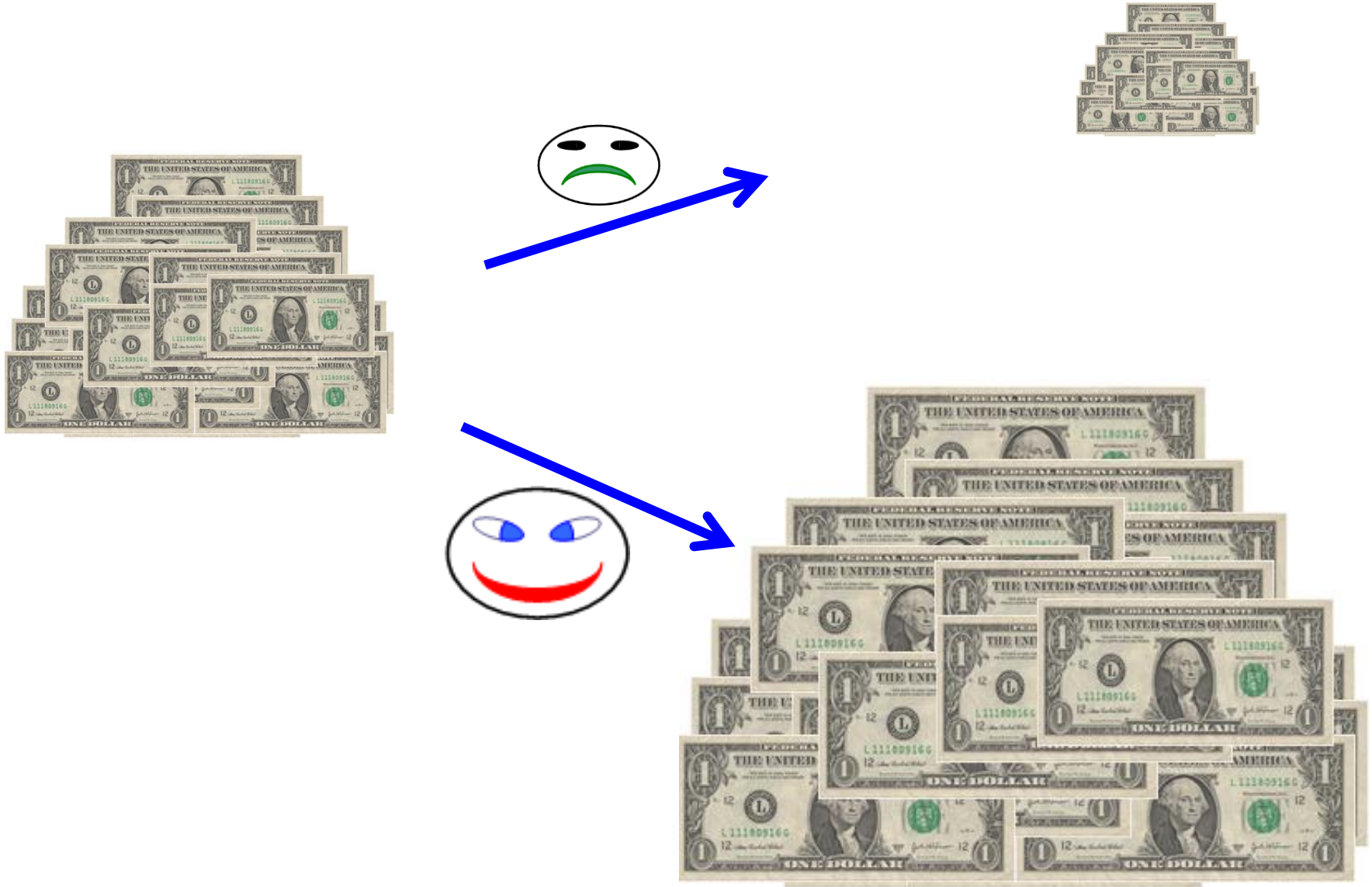
Average annual earnings/employee: \$65K



Tunc Doluca  
BSEE IASTATE  
(1979)



# Considerable Cash Flow Inherent in the Semiconductor Industry





# Essentially All Activities Driven by Economic Considerations



- Many Designs Cost Tens of Millions of Dollars
- Mask Set and Production of New Circuit Approaching \$2 Million
- New Foundries Costs Approaching \$10 Billion (few players in World can compete)
- Many Companies Now Contract Fabrication (Fabless Semiconductor Companies)
- Time to Market is Usually Critical
- Single Design Error Often Causes Months of Delay and Requires New Mask Set
- Potential Rewards in Semiconductor Industry are Very High

**Will emphasize economic considerations throughout this course**

# Understanding of the Big Picture is Critical



# Solving Design Problems can be Challenging

Be sure to solve the right problem !



# How can complex circuits with a very large number of transistors be efficiently designed with low probability of error?

 Many designers often work on a single design

 Single error in reasoning, in circuit design, or in implementing circuit on silicon generally results in failure

- Design costs and fabrication costs for test circuits are very high
  - Design costs for even rather routine circuits often a few million dollars and some much more
  - Masks and processing for state of the art processes often between \$1M and \$2M
- Although much re-use is common on many designs, considerable new circuits that have never been designed or tested are often required
- Time to market critical – missing a deadline by even a week or two may kill the market potential

# Single Errors Usually Cause Circuit Failure

- How many components were typical of lab experiments in EE 201 and EE 230?
- Has anyone ever made an error in the laboratory of these courses ? (wrong circuit, incomplete understanding, wrong wiring, wrong component values, imprecise communication, frustration .....)
- How many errors are made in a typical laboratory experiment in these courses?
- How many errors per hour might have occurred?

# Single Errors Usually Cause Circuit Failure

## **Consider an extremely complicated circuit**

- with requirements to do things that have never been done before
- with devices that are not completely understood
- that requires several billion transistors
- that requires 200 or more engineers working on a project full-time for 3 years
- with a company investment of many million dollars
- with an expectation that nobody makes a single error

**Is this a challenging problem for all involved?**

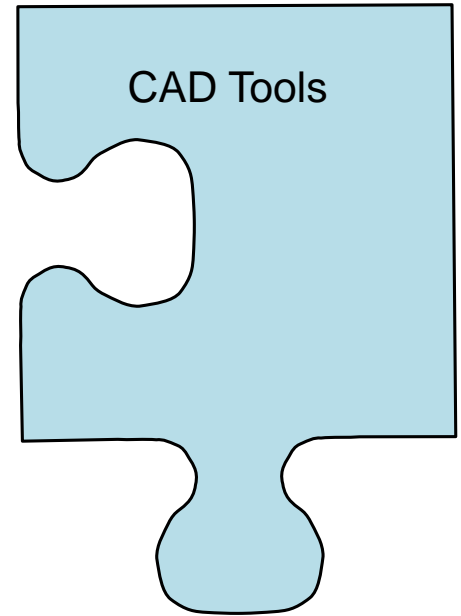
# How can complex circuits with a very large number of transistors be efficiently designed with low probability of error?

- CAD tools and CAD-tool environment critical for success today
- Small number of VLSI CAD toolset vendors
- CAD toolset helps the engineer and it is highly unlikely the CAD tools will replace the design engineer
- An emphasis in this course is placed on using toolset to support the design process

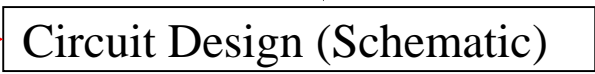


# CAD Environment for Integrated Circuit Design

- Typical Tool Flow
  - (See Chapter 14 of Text)
- Laboratory Experiments in Course



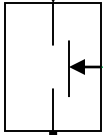
## System Description



## Simulation Results



## DRC Error Report



Fabrication

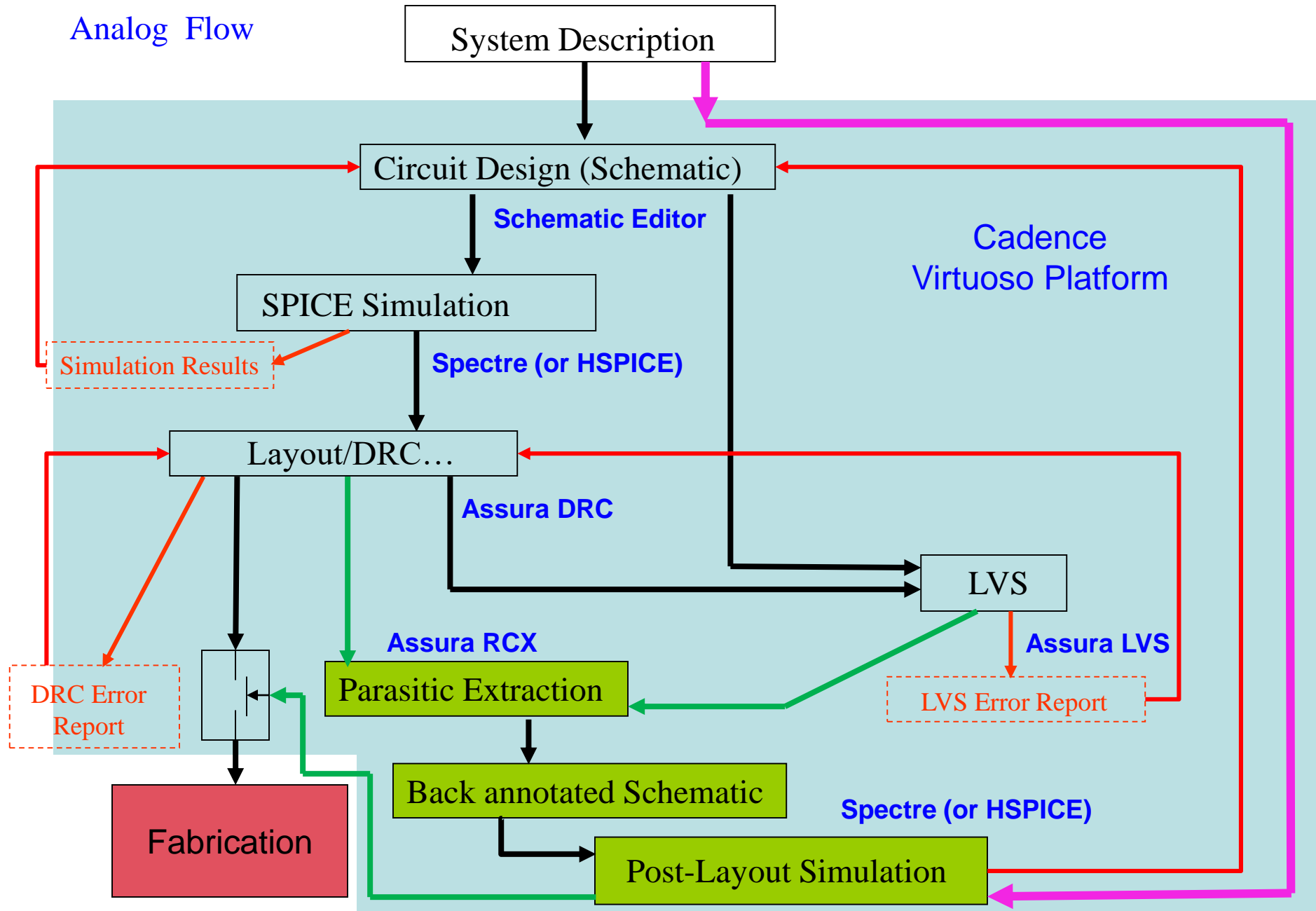


## LVS Error Report

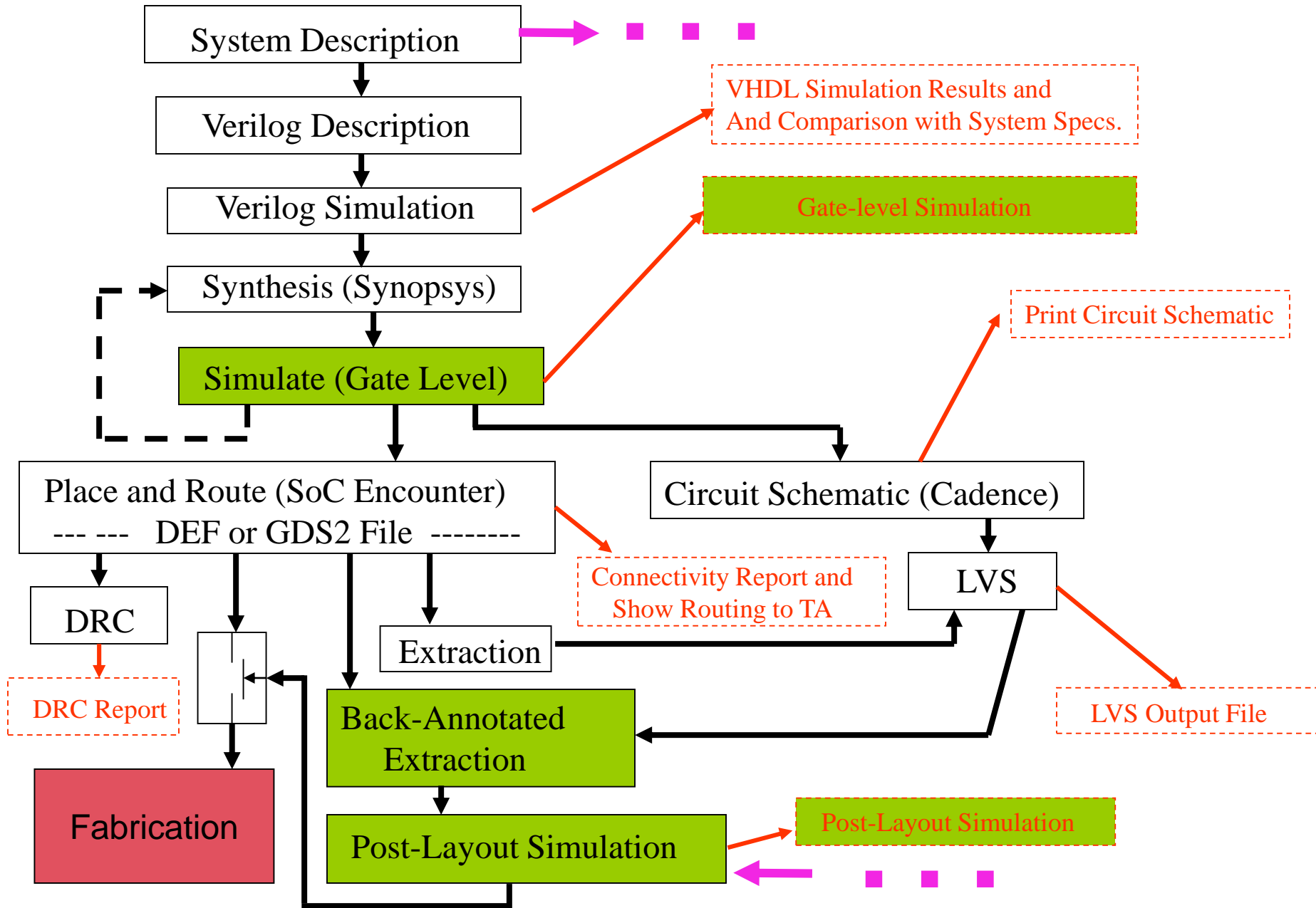


# VLSI Design Flow Summary

Analog Flow

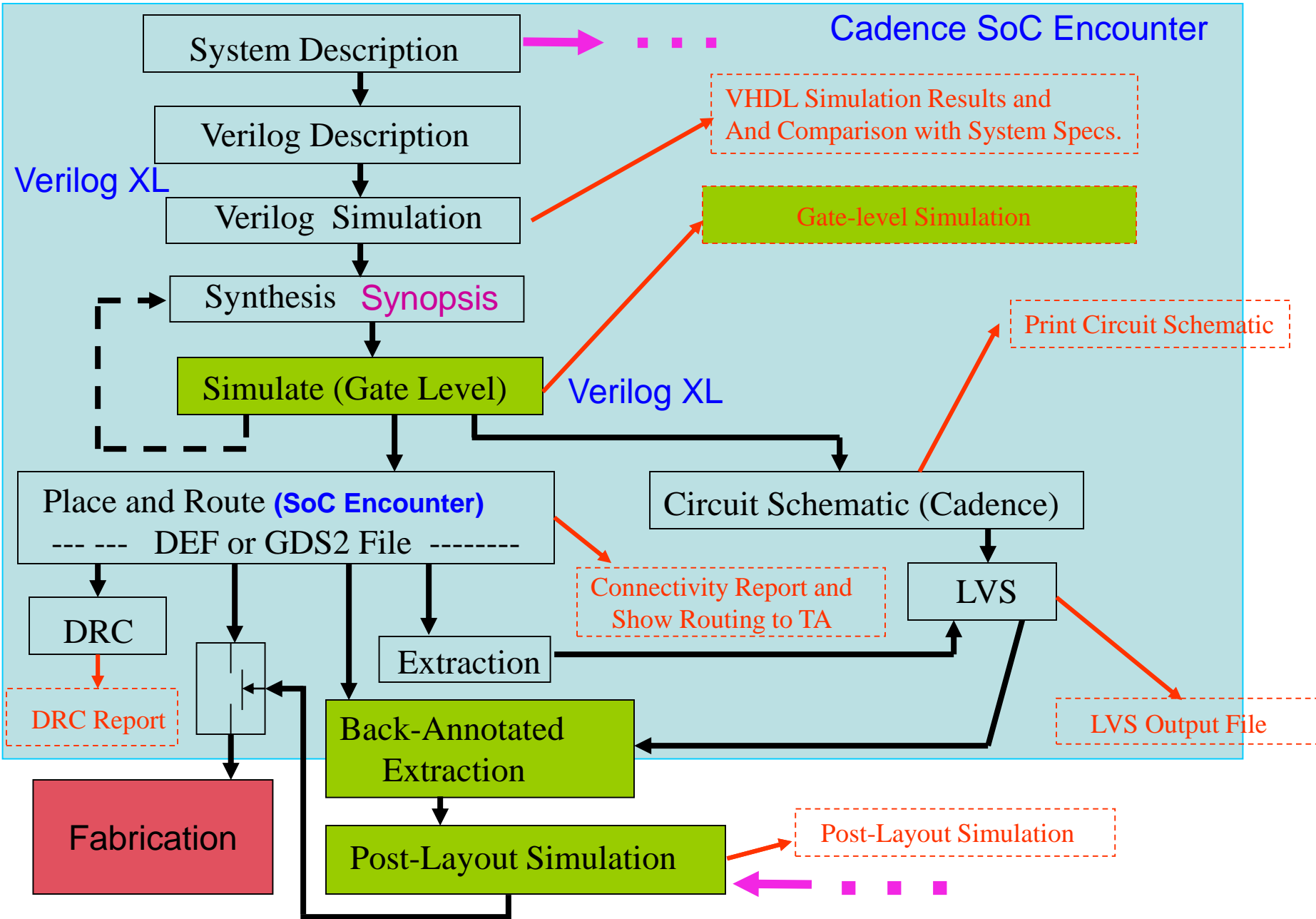


# VLSI Design Flow Summary



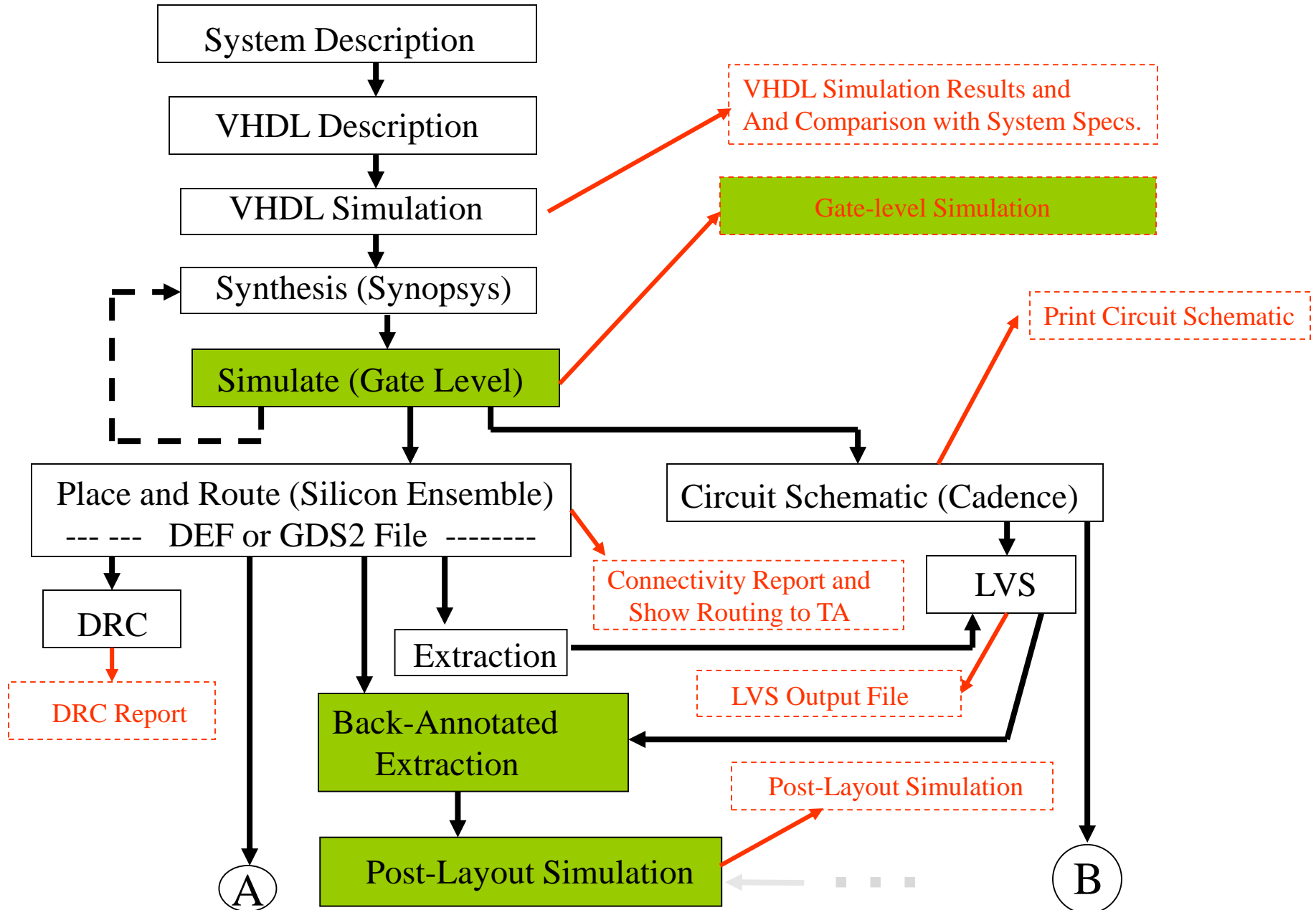
# VLSI Design Flow Summary

Digital Flow



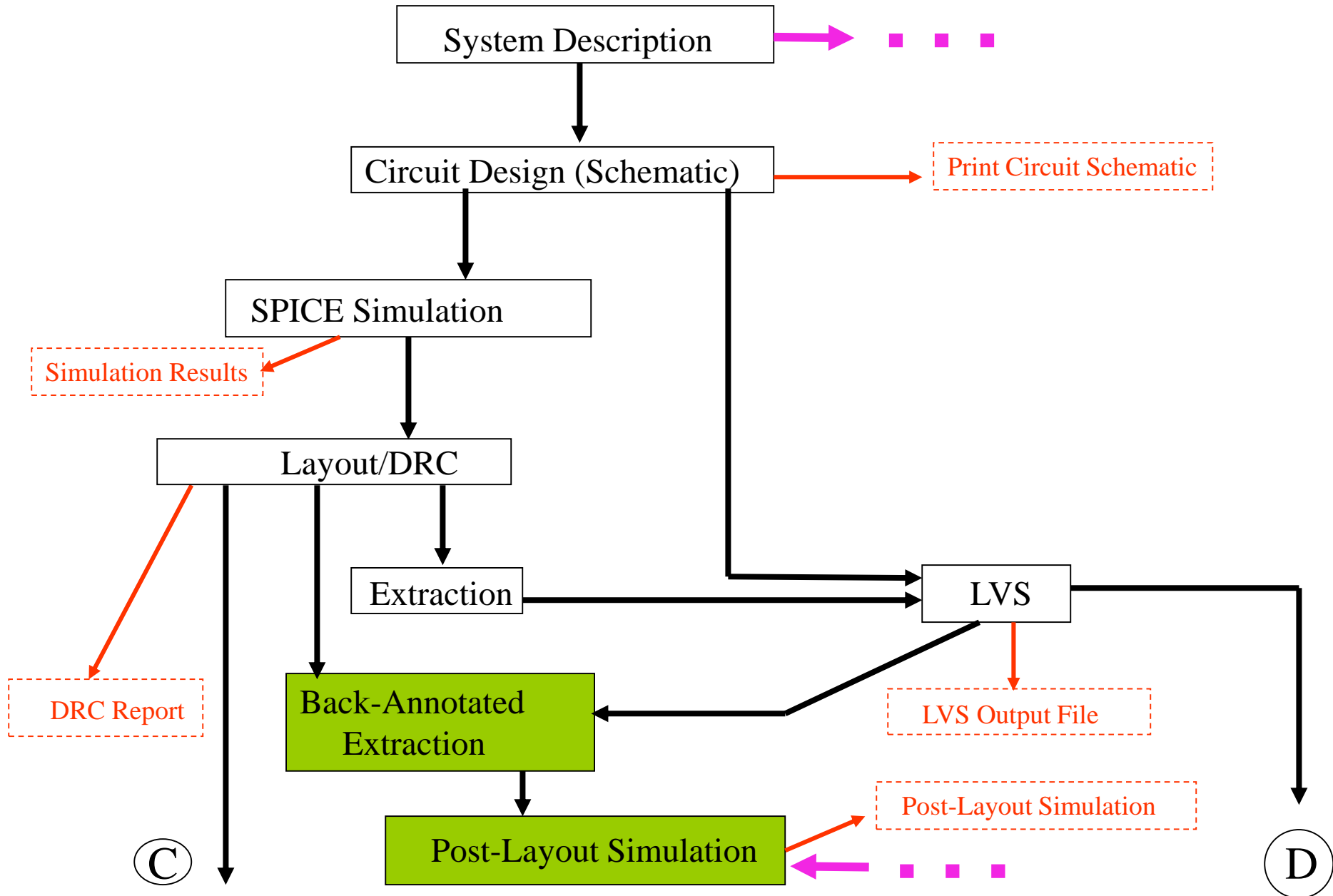
# VLSI Design Flow Summary

## Mixed Signal Flow (Digital Part)



# VLSI Design Flow Summary

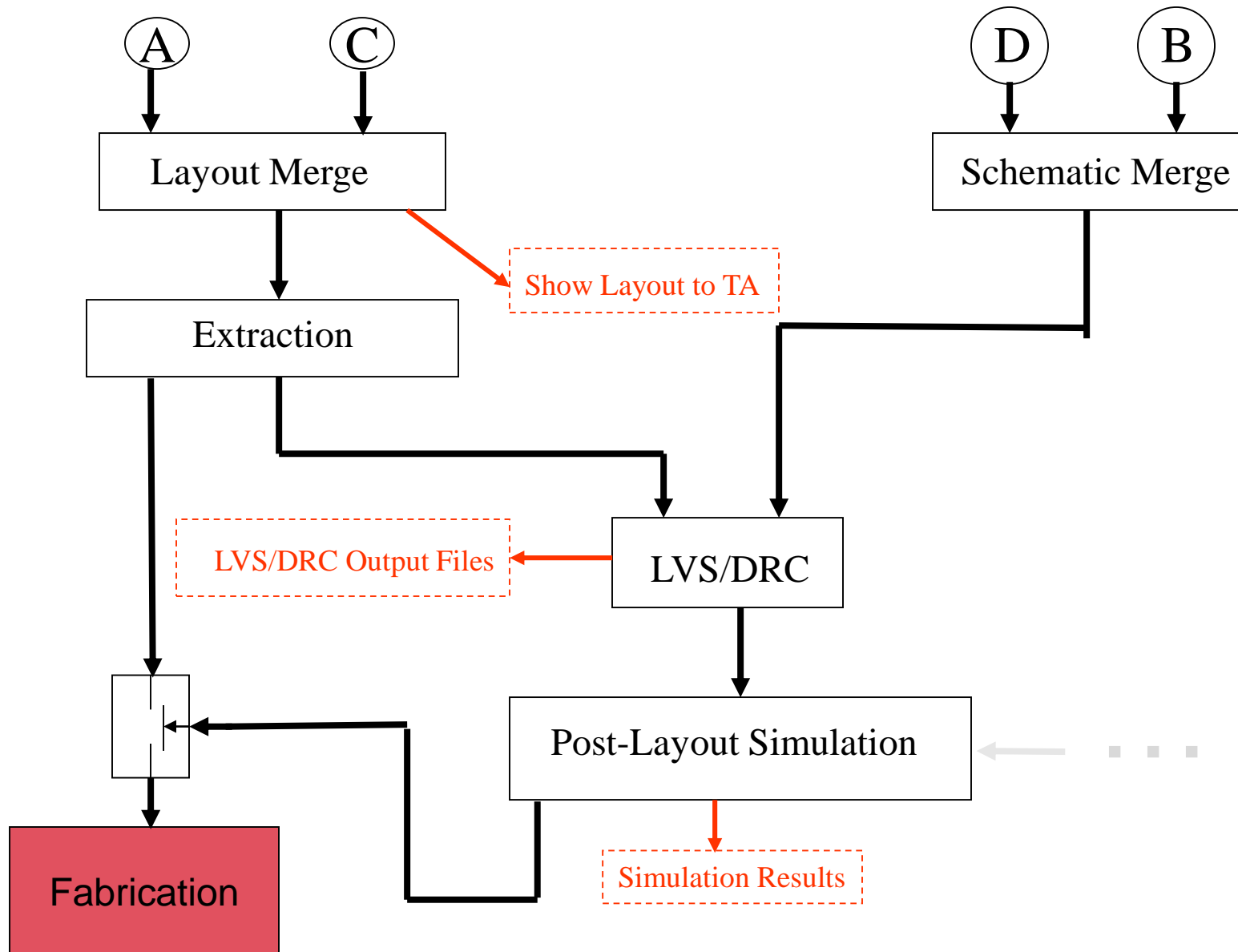
## Mixed-Signal Flow (Analog Part)





# VLSI Design Flow Summary

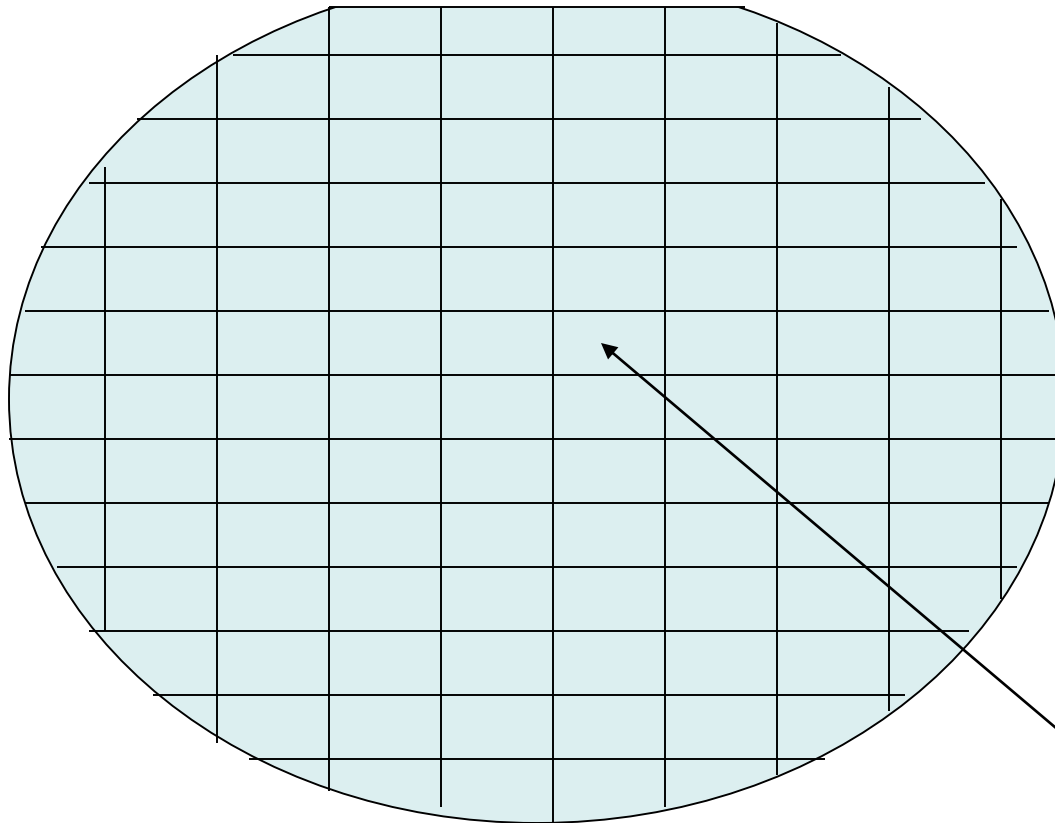
## Mixed-Signal Flow (Analog-Digital Merger)



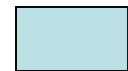
# Comments

- The Analog Design Flow is often used for small digital blocks or when particular structure or logic styles are used in digital systems
- Variants of these flows are widely used and often personalized by a given company or for specific classes of circuits

# Wafer

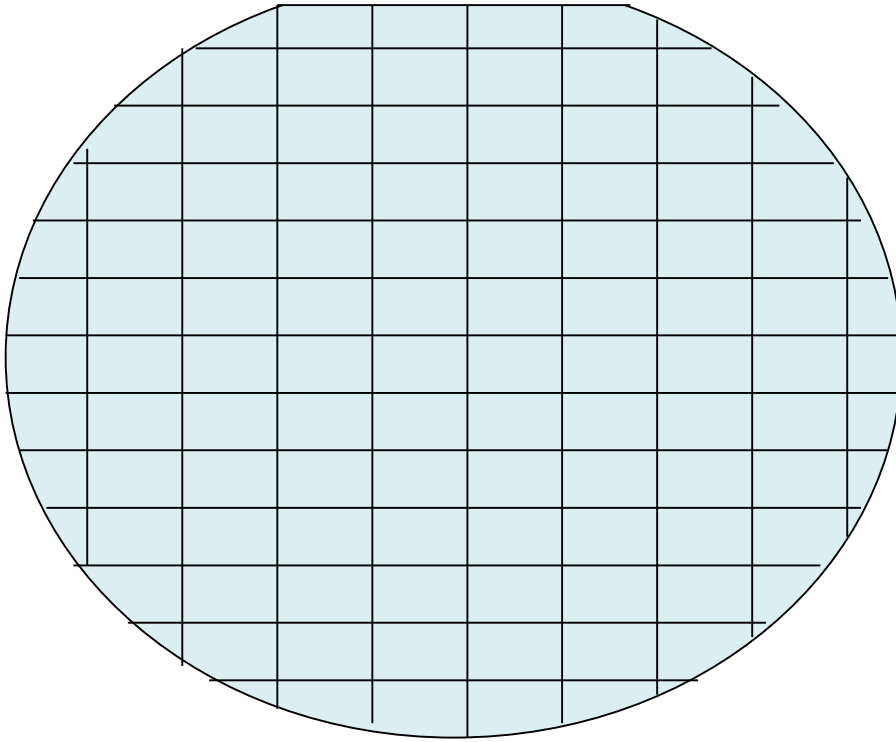


- 6 inches to 18 inches in diameter
- All complete cells ideally identical
- flat edge
- very large number of die if die size is small



die

# Why are wafers round?



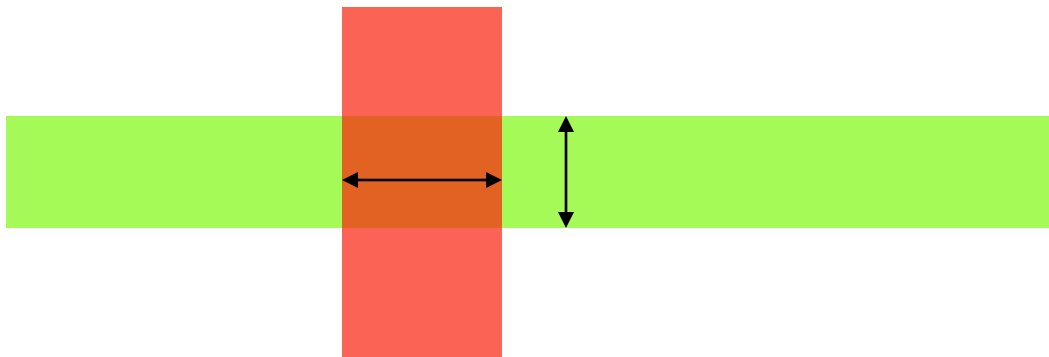
- Ingot spins (rotates) as crystal is being made (dominant reason)
- Edge loss would be larger with rectangular wafers
- Heat is more uniformly distributed during processing
- Size of furnace is smaller for round wafers
- Wafers are spun during application of photoresist and even coatings is critical
- Optics for projection are better near center of image

# Feature Size

Feature size is the minimum lateral feature size that can be **reliably** manufactured



Often given as either  
feature size or pitch

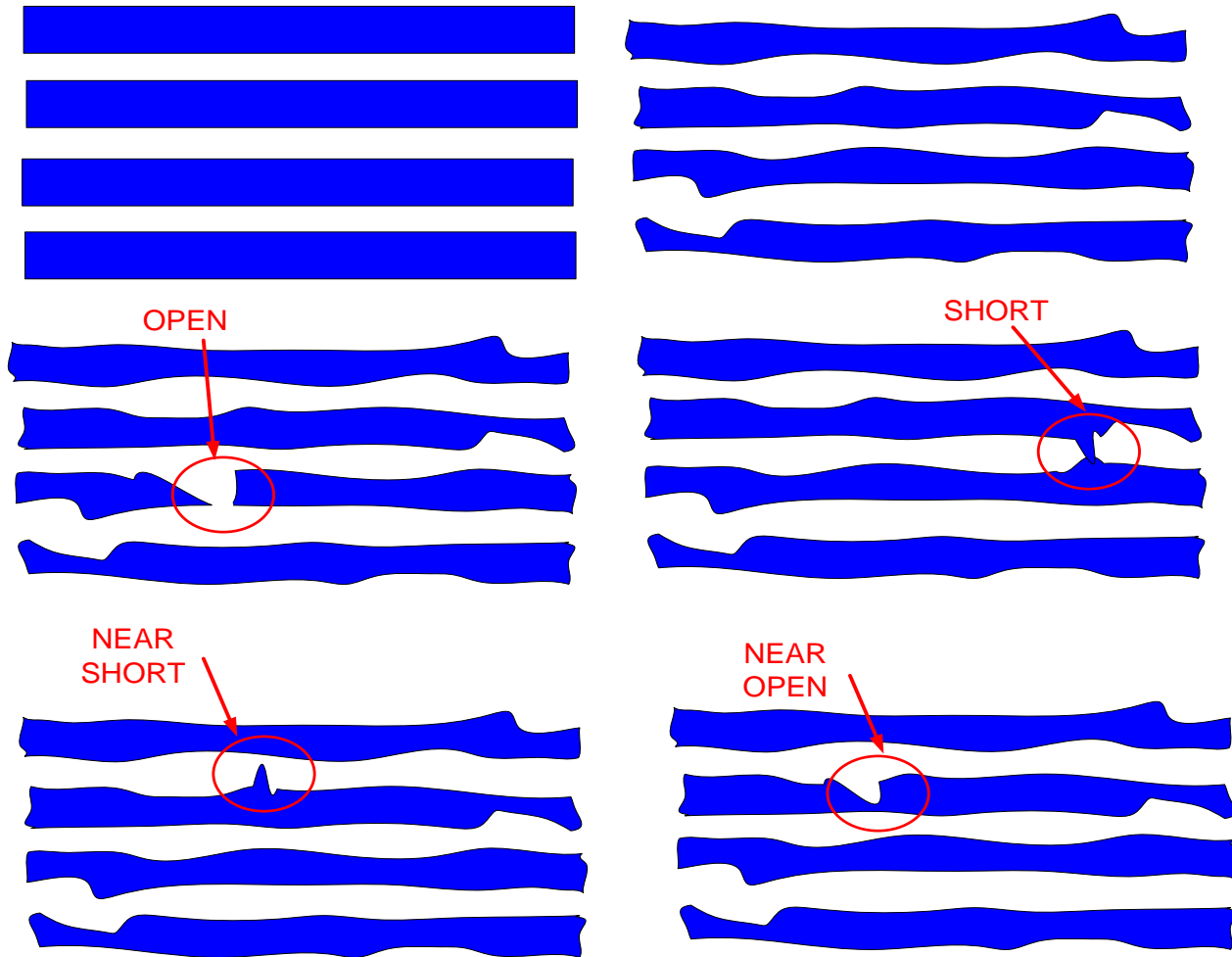


Minimum feature size often  
identical for different features

Extremely challenging to  
decrease minimum feature  
size in a new process

# Reliability Problems

## Desired Features



Actual features show some variability (dramatically exaggerated here !!!!)

**End of Lecture 3**